Session Title:	[WeA1] CMP Innovations
Session Date:	November 13 (Wed.), 2024
Session Time:	09:00-10:40
Session Room:	Room A (Capri Room, 2F, Paradise Hotel Busan)
Session Chair:	Prof. Tae-Dong Kim (Hannam Univ., Korea)

[WeA1-1] [Invited] 09:00-09:30

Surface-Structured Pads for Scratch-Less Chemical Mechanical Polishing

Sanha Kim (KAIST, Korea)

[WeA1-2] [Invited] 09:30-10:00

The Mechanical Aspects of Chemical Mechanical Planarization (CMP): Its Known, Unknown, and Challenges in Industry

Wei-Tsu Tseng (IBM Semiconductor Tech. Research, USA)

[WeA1-3] 10:00-10:20

Study on CMP Performance of Ceria Nanoparticles according to Differences in Synthesis Method

Sohee Hwang and Woonjung Kim (Hannam Univ., Korea)

[WeA1-4] 10:20-10:40

Dependencies of Super-Fine Wet-Ceria Abrasive on Solubility Enhancement Surfactant Having Amine Functional Group

Pil-Su Kim, Min-Uk Jeon, Ju-Yeon Kim, Eun-Ha Park, Se-Hui Lee, Hye-Min Lee (Hanyang Univ., Korea), Jin-Hyung Park (ENF Tech. Inc., Korea), Jin-Sub Park, and Jea-Gun Park (Hanyang Univ., Korea)